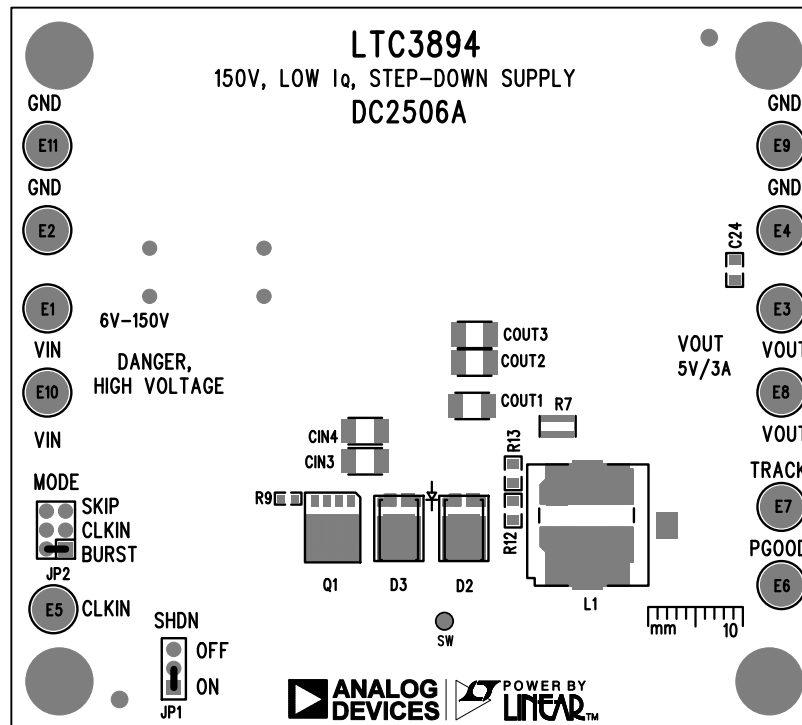
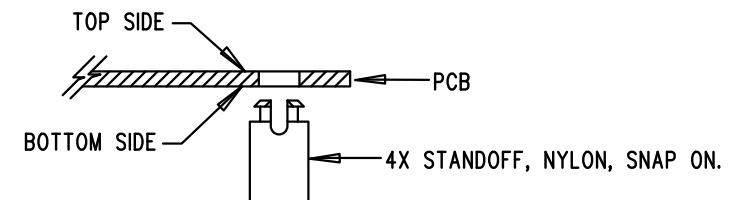


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	3	PRODUCTION	DB	01-09-18



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
6. INSTALL 4 STANDOFFS AT AS SHOWN BELOW:



APPROVALS		ANALOG DEVICES POWER BY LINEAR™ www.linear.com FOR ADI CUSTOMER USE ONLY		
PCB DES.	LT	TITLE: TOP ASSEMBLY DRAWING 150V, LOW Iq, STEP-DOWN SUPPLY		
APP ENG.	DB			
		SIZE	IC NO.	REV.
		N/A	LTC3894EFE DEMO BOARD 2506A	3
SCALE = NONE		FILENAME: DC2506A-3.PCB		SHT 1 OF 2